TOSHIBA Field-Effect Transistor Silicon N Channel MOS Type (U-MOSIV)

# SSM3K7002BSU

**High-Speed Switching Applications Analog Switch Applications** 

Small package

Low ON-resistance :  $R_{DS(ON)} = 3.3 \Omega \text{ (max) } (@V_{GS} = 4.5 \text{ V})$ 

> :  $R_{DS(ON)} = 2.6 \Omega \text{ (max) } (@V_{GS} = 5 \text{ V})$ :  $R_{DS(ON)} = 2.1 \Omega \text{ (max) } (@V_{GS} = 10 \text{ V})$

## Absolute Maximum Ratings (Ta = 25℃)

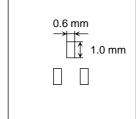
Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	60	V	
Gate-source voltage		V <sub>GSS</sub>	± 20	V	
Drain current	DC	I <sub>D</sub>	200	mA	
	Pulse	I <sub>DP</sub>	800		
Power dissipation (Ta = 25℃)		P <sub>D</sub> (Note 1)	150	mW	
Channel temperature		T <sub>ch</sub>	150	C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

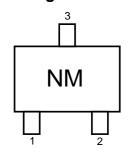
Please design the appropriate reliability upon reviewing the

Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

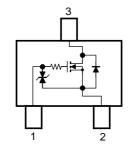
Note 1: Mounted on FR4 board  $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ mm}, \text{ Cu Pad: } 0.6 \text{mm}^2 \times 3)$ 



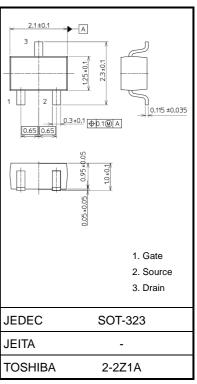
#### Marking



# **Equivalent Circuit (top view)**



Unit: mm



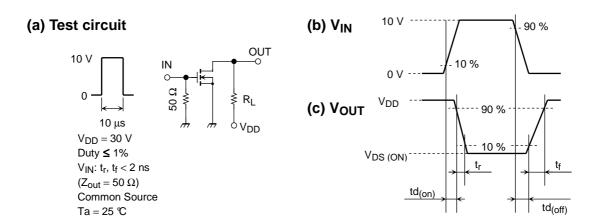
Weight: 5.5 mg (typ.)

### Electrical Characteristics (Ta = 25℃)

Cha	racteristics	Symbol	Test Condition		Min	Тур	Max	Unit	
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$		_	_	±10	μΑ	
Drain-source breakdown voltage		V (BR) DSS	$I_D = 0.1 \text{ mA}, V_{GS} = 0 \text{ V}$		60	_	_	V	
		V (BR) DSX	$I_D = 0.1 \text{ mA}, V_{GS} = -10 \text{ V}$		45	_	_	V	
Drain cutoff curre	nt	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V		_	_	1	μΑ	
Gate threshold vo	ltage	$V_{th}$	$V_{DS} = 10 \text{ V}, I_{D} = 0.25 \text{ mA}$		1.0	_	2.5	V	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 200 \text{ mA}$	(Note 2)	225	_	_	mS	
Drain-source ON-resistance		R <sub>DS</sub> (ON)	$I_D = 500 \text{ mA}, V_{GS} = 10 \text{ V}$	(Note 2)	_	1.62	2.1	Ω	
			$I_D = 100 \text{ mA}, V_{GS} = 5 \text{ V}$	(Note 2)	_	1.77	2.6		
			I <sub>D</sub> = 100 mA, V <sub>GS</sub> = 4.5 V	(Note 2)	_	1.81	3.3		
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		_	17.0	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>			_	1.9	_		
Output capacitance		Coss			_	3.6	_		
Switching time	Turn-on delay time	td <sub>(on)</sub>	$V_{DD} = 30 \text{ V}, I_D = 200 \text{ mA}, V_{GS} = 0 \text{ to } 10 \text{ V}$		_	2.5	5.0	ns	
	Turn-off delay time	td <sub>(off)</sub>			_ ′	18	55	115	
Drain-source forward voltage		V <sub>DSF</sub>	$I_D = -200 \text{ mA}, V_{GS} = 0 \text{ V}$	(Note 2)	_	-0.84	-1.2	٧	

Note2: Pulse test

#### **Switching Time Test Circuit**

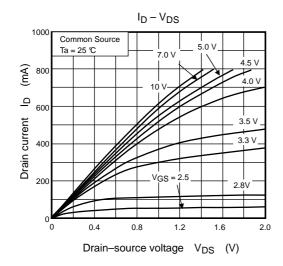


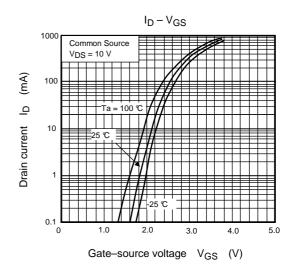
#### **Precaution**

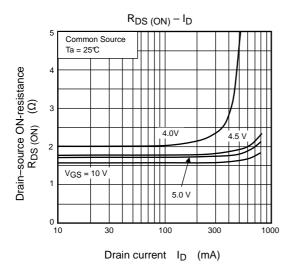
Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current (I<sub>D</sub>) to be low (0.25 mA for the SSM3K7002BSU). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ . Take this into consideration when using the device

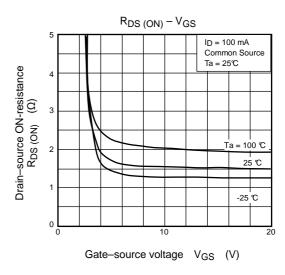
# **Handling Precaution**

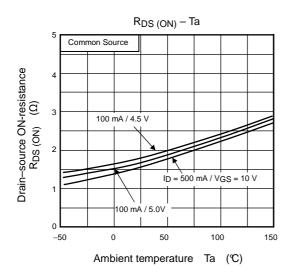
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

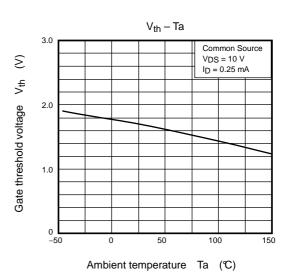




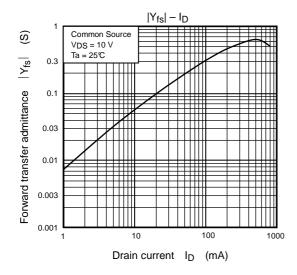


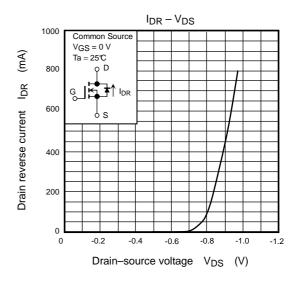


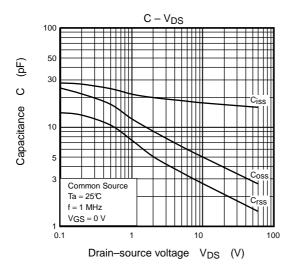


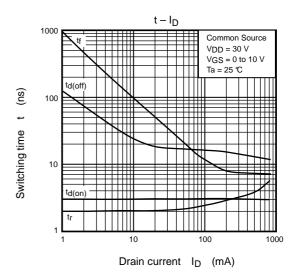


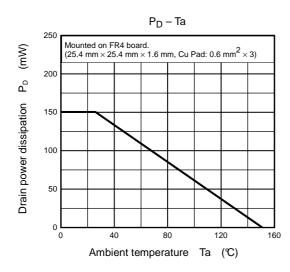
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